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# MC100LVEP111

## 2.5V / 3.3V 2:1:10 Differential ECL/PECL/HSTL Clock Driver

### Description

The MC100LVEP111 is a low skew 2:1:10 differential driver, designed with clock distribution in mind, accepting two clock sources into an input multiplexer. The PECL input signals can be either differential or single-ended (if the  $V_{BB}$  output is used). HSTL inputs can be used when the LVEP111 is operating under PECL conditions.

The LVEP111 specifically guarantees low output-to-output skew. Optimal design, layout, and processing minimize skew within a device and from device to device.

To ensure tightest skew, both sides of differential outputs identically terminate into  $50\ \Omega$  even if only one output is being used. If an output pair is unused, both outputs may be left open (unterminated) without affecting skew.

The MC100LVEP111, as with most other ECL devices, can be operated from a positive  $V_{CC}$  supply in PECL mode. This allows the LVEP111 to be used for high performance clock distribution in +3.3 V or +2.5 V systems. Single-ended CLK input operation is limited to a  $V_{CC} \geq 3.0\ \text{V}$  in PECL mode, or  $V_{EE} \leq -3.0\ \text{V}$  in NECL mode when using  $V_{BB}$  (See Figure 11). Full operating range is available when using an external voltage reference (See Figure 10). Designers can take advantage of the LVEP111's performance to distribute low skew clocks across the backplane or the board.

### Features

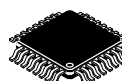
- 85 ps Typical Device-to-Device Skew
- 20 ps Typical Output-to-Output Skew
- Jitter Less than 1 ps RMS
- Additive RMS Phase Jitter: 60 fs @ 156.25 MHz, Typ.
- Maximum Frequency > 3 GHz Typical
- $V_{BB}$  Output
- 430 ps Typical Propagation Delay
- The 100 Series Contains Temperature Compensation
- PECL and HSTL Mode Operating Range:  $V_{CC} = 2.375\ \text{V}$  to  $3.8\ \text{V}$  with  $V_{EE} = 0\ \text{V}$
- NECL Mode Operating Range:  $V_{CC} = 0\ \text{V}$  with  $V_{EE} = -2.375\ \text{V}$  to  $-3.8\ \text{V}$
- Open Input Default State
- LVDS Input Compatible
- Fully Compatible with MC100EP111
- These are Pb-Free Devices



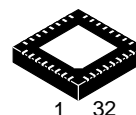
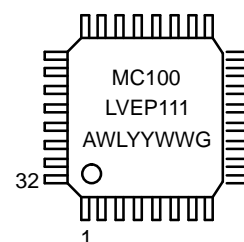
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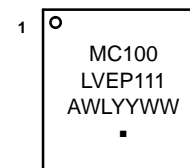
### MARKING DIAGRAMS\*



LQFP-32  
FA SUFFIX  
CASE 873A



QFN32  
MN SUFFIX  
CASE 488AM



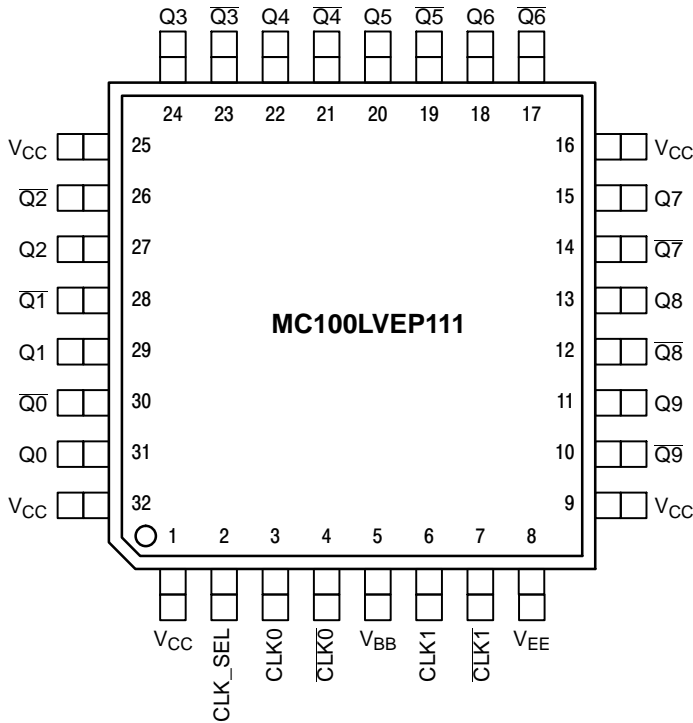
A = Assembly Location  
WL = Wafer Lot  
YY = Year  
WW = Work Week  
G or ▪ = Pb-Free Package

\*For additional marking information, refer to Application Note AND8002/D.

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 11 of this data sheet.

# MC100LVEP111



Warning: All  $V_{CC}$  and  $V_{EE}$  pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. LQFP-32 Pinout (Top View)

Table 1. PIN DESCRIPTION

PIN	FUNCTION
CLK0*, $\overline{CLK0}$ **	ECL/PECL/HSTL CLK Input
CLK1*, $\overline{CLK1}$ **	ECL/PECL/HSTL CLK Input
Q0:9, $\overline{Q0}$ :9	ECL/PECL Outputs
CLK_SEL*	ECL/PECL Active Clock Select Input
$V_{BB}$	Reference Voltage Output
$V_{CC}$	Positive Supply
$V_{EE}$	Negative Supply
EP	The exposed pad (EP) on the package bottom must be attached to a heat-sinking conduit. The exposed pad may only be electrically connected to $V_{EE}$ .

\* Pins will default LOW when left open.

\*\* Pins will default to  $2/3V_{CC}$  when left open.

Table 2. FUNCTION TABLE

CLK_SEL	Active Input
L	CLK0, $\overline{CLK0}$
H	CLK1, $\overline{CLK1}$

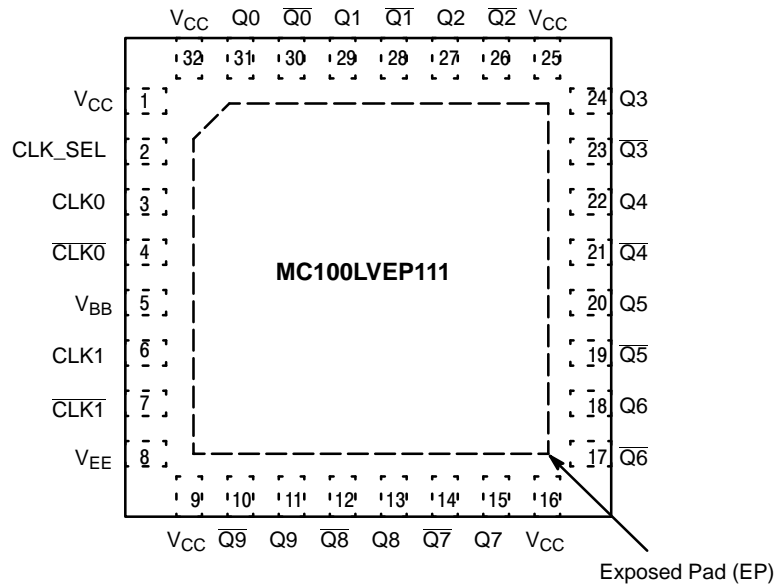


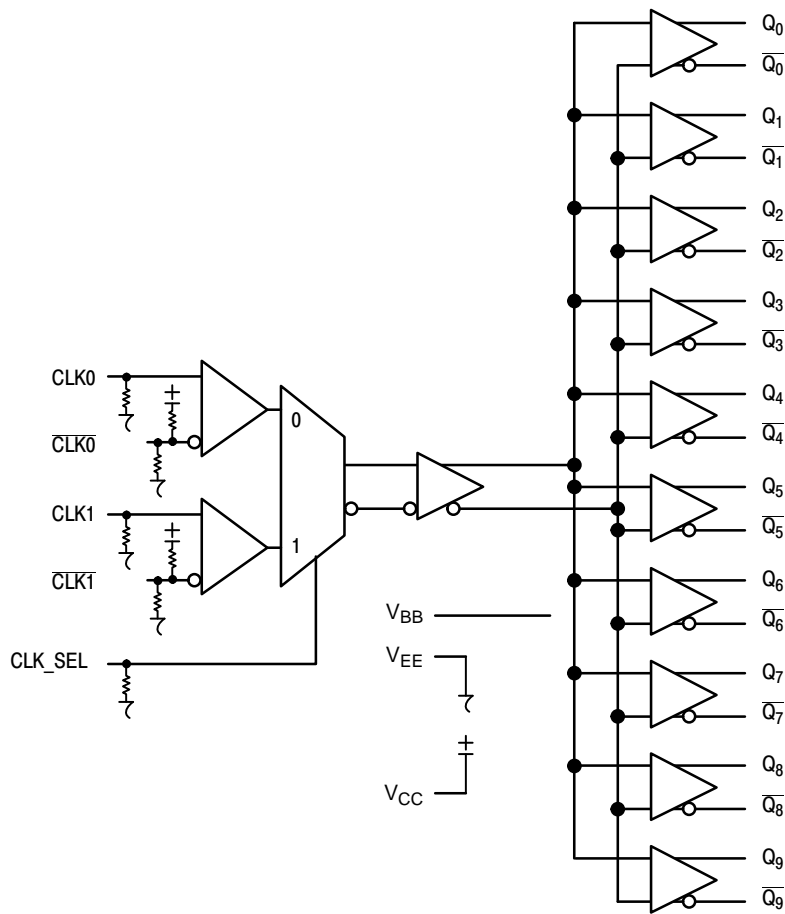
Figure 2. QFN-32 Pinout (Top View)

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**Table 3. ATTRIBUTES**

Characteristics		Value	
Internal Input Pulldown Resistor		75 kΩ	
Internal Input Pullup Resistor		37.5 kΩ	
ESD Protection	Human Body Model Machine Model Charged Device Model	> 2 kV > 100 V > 2 kV	
Moisture Sensitivity (Note 1)		Pb Pkgs	Pb-Free Pkgs
		LQFP Level 2	Level 2
		QFN Level 1	Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
Transistor Count		602 Devices	
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test			

1. For additional information, refer to Application Note AND8003/D.



**Figure 3. Logic Diagram**

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**Table 4. MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
$V_{CC}$	PECL Mode Power Supply	$V_{EE} = 0\text{ V}$		6	V
$V_{EE}$	NECL Mode Power Supply	$V_{CC} = 0\text{ V}$		-6	V
$V_I$	PECL Mode Input Voltage NECL Mode Input Voltage	$V_{EE} = 0\text{ V}$ $V_{CC} = 0\text{ V}$	$V_I \leq V_{CC}$ $V_I \geq V_{EE}$	6 -6	V V
$I_{out}$	Output Current	Continuous Surge		50 100	mA mA
$I_{BB}$	$V_{BB}$ Sink/Source			$\pm 0.5$	mA
$T_A$	Operating Temperature Range			-40 to +85	$^{\circ}\text{C}$
$T_{stg}$	Storage Temperature Range			-65 to +150	$^{\circ}\text{C}$
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	LQFP-32 LQFP-32	80 55	$^{\circ}\text{C}/\text{W}$ $^{\circ}\text{C}/\text{W}$
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	LQFP-32	12 to 17	$^{\circ}\text{C}/\text{W}$
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	QFN-32 QFN-32	31 27	$^{\circ}\text{C}/\text{W}$ $^{\circ}\text{C}/\text{W}$
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	2S2P	QFN-32	12	$^{\circ}\text{C}/\text{W}$
$T_{sol}$	Wave Solder Pb Pb-Free (QFN-32 Only)	< 3 sec @ 248 $^{\circ}\text{C}$ < 3 sec @ 260 $^{\circ}\text{C}$		265 265	$^{\circ}\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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**Table 5. PECL DC CHARACTERISTICS**  $V_{CC} = 2.5\text{ V}$ ;  $V_{EE} = 0\text{ V}$  (Note 2)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current	60	90	120	60	90	120	60	90	120	mA
$V_{OH}$	Output HIGH Voltage (Note 3)	1355	1480	1605	1355	1480	1605	1355	1480	1605	mV
$V_{OL}$	Output LOW Voltage (Note 3)	505	730	900	505	730	900	505	730	900	mV
$V_{IH}$	Input HIGH Voltage (Single-Ended) (Note 4)	1335		1620	1335		1620	1275		1620	mV
$V_{IL}$	Input LOW Voltage (Single-Ended) (Note 4)	505		875	505		875	505		875	mV
$V_{IHCMR}$	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 5)	1.2		2.5	1.2		2.5	1.2		2.5	V
$I_{IH}$	Input HIGH Current			150			150			150	$\mu\text{A}$
$I_{IL}$	Input LOW Current	CLK CLK	0.5 -150		0.5 -150			0.5 -150			$\mu\text{A}$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

- Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary + 0.125 V to -1.3 V.
- All loading with 50  $\Omega$  to  $V_{EE}$ .
- Do not use  $V_{BB}$  at  $V_{CC} < 3.0\text{ V}$ .
- $V_{IHCMR}$  min varies 1:1 with  $V_{EE}$ ,  $V_{IHCMR}$  max varies 1:1 with  $V_{CC}$ . The  $V_{IHCMR}$  range is referenced to the most positive side of the differential input signal.

**Table 6. PECL DC CHARACTERISTICS**  $V_{CC} = 3.3\text{ V}$ ;  $V_{EE} = 0\text{ V}$  (Note 6)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current	60	90	120	60	90	120	60	90	120	mA
$V_{OH}$	Output HIGH Voltage (Note 7)	2155	2280	2405	2155	2280	2405	2155	2280	2405	mV
$V_{OL}$	Output LOW Voltage (Note 7)	1305	1530	1700	1305	1530	1700	1305	1530	1700	mV
$V_{IH}$	Input HIGH Voltage (Single-Ended)	2135		2420	2135		2420	2135		2420	mV
$V_{IL}$	Input LOW Voltage (Single-Ended)	1305		1675	1305		1675	1305		1675	mV
$V_{BB}$	Output Reference Voltage (Note 8)	1775	1875	1975	1775	1875	1975	1775	1875	1975	mV
$V_{IHCMR}$	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 9)	1.2		3.3	1.2		3.3	1.2		3.3	V
$I_{IH}$	Input HIGH Current			150			150			150	$\mu\text{A}$
$I_{IL}$	Input LOW Current	CLK CLK	0.5 -150		0.5 -150			0.5 -150			$\mu\text{A}$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

- Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary + 0.925 V to -0.5 V.
- All loading with 50  $\Omega$  to  $V_{CC} - 2.0\text{ V}$ .
- Single ended input operation is limited  $V_{CC} \geq 3.0\text{ V}$  in PECL mode.
- $V_{IHCMR}$  min varies 1:1 with  $V_{EE}$ ,  $V_{IHCMR}$  max varies 1:1 with  $V_{CC}$ . The  $V_{IHCMR}$  range is referenced to the most positive side of the differential input signal.

**Table 7. NECL DC CHARACTERISTICS**  $V_{CC} = 0\text{ V}$ ,  $V_{EE} = -2.375\text{ V}$  to  $-3.8\text{ V}$  (Note 10)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{EE}$	Power Supply Current	60	90	120	60	90	120	60	90	120	mA
$V_{OH}$	Output HIGH Voltage (Note 11)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1020	-895	mV
$V_{OL}$	Output LOW Voltage (Note 11)	-1995	-1770	-1600	-1995	-1770	-1600	-1995	-1770	-1600	mV

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**Table 7. NECL DC CHARACTERISTICS**  $V_{CC} = 0\text{ V}$ ,  $V_{EE} = -2.375\text{ V}$  to  $-3.8\text{ V}$  (Note 10)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$V_{IH}$	Input HIGH Voltage (Single-Ended)	-1165		-880	-1165		-880	-1165		-880	mV
$V_{IL}$	Input LOW Voltage (Single-Ended)	-1995		-1625	-1995		-1625	-1995		-1625	mV
$V_{BB}$	Output Reference Voltage (Note 12)	-1525	-1425	-1325	-1525	-1425	-1325	-1525	-1425	-1325	mV
$V_{IHCMR}$	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 13)	$V_{EE} + 1.2$		0.0	$V_{EE} + 1.2$		0.0	$V_{EE} + 1.2$		0.0	V
$I_{IH}$	Input HIGH Current			150			150			150	$\mu\text{A}$
$I_{IL}$	Input LOW Current CLK CLK	0.5 -150			0.5 -150			0.5 -150			$\mu\text{A}$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm.

10. Input and output parameters vary 1:1 with  $V_{CC}$ .

11. All loading with  $50\ \Omega$  to  $V_{CC} - 2.0\text{ V}$ .

12. Single ended input operation is limited  $V_{EE} \leq -3.0\text{ V}$  in NECL mode.

13.  $V_{IHCMR}$  min varies 1:1 with  $V_{EE}$ .  $V_{IHCMR}$  max varies 1:1 with  $V_{CC}$ . The  $V_{IHCMR}$  range is referenced to the most positive side of the differential input signal.

**Table 8. HSTL DC CHARACTERISTICS**  $V_{CC} = 2.375$  to  $3.8\text{ V}$ ,  $V_{EE} = 0\text{ V}$

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$V_{IH}$	Input HIGH Voltage	1200			1200			1200			mV
$V_{IL}$	Input LOW Voltage			400			400			400	mV
$V_x$	Input Crossover Voltage	680		900	680		900	680		900	mV
$I_{CC}$	Power Supply Current	70	100	120	70	100	120	70	100	120	mA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm.

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**Table 9. AC CHARACTERISTICS**  $V_{CC} = 0\text{ V}$ ;  $V_{EE} = -2.375\text{ to }-3.8\text{ V}$  or  $V_{CC} = 2.375\text{ to }3.8\text{ V}$ ;  $V_{EE} = 0\text{ V}$  (Note 14)

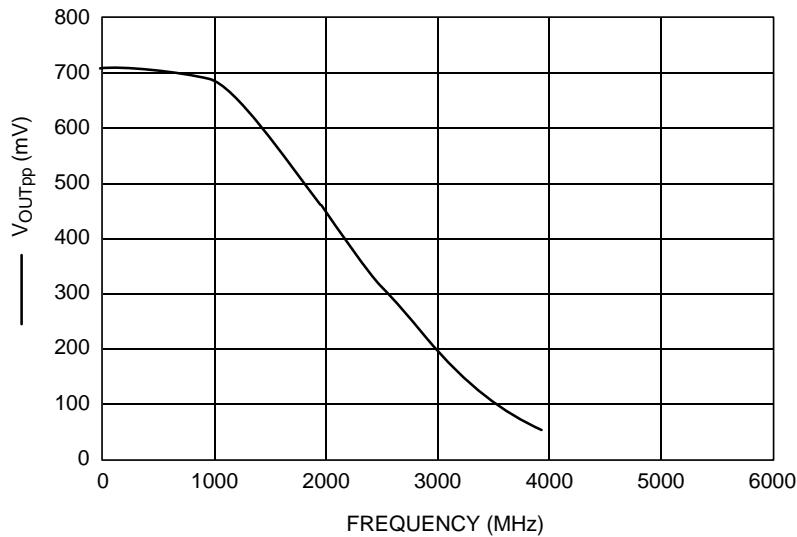
Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{\text{maxPECL/HSTL}}$	Maximum Frequency (Figure 4)		3			3			3		GHz
$t_{\text{PLH}}$ $t_{\text{PHL}}$	Propagation Delay (Differential Configuration)	325	400	475	350	430	500	375	510	590	ps
$t_{\text{skew}}$	Within-Device Skew (Note 15) Within-Device Skew @ 2.5 V (Note 15) Device-to-Device Skew (Note 16)		20 20 85	25 25 150		20 20 85	25 25 150		25 20 85	35 25 150	ps
$t_{\text{JITTER}}$	CLOCK Random Jitter (RMS) @ $\leq 0.5\text{ GHz}$ @ $\leq 1.0\text{ GHz}$ @ $\leq 1.5\text{ GHz}$ @ $\leq 2.0\text{ GHz}$ @ $\leq 2.5\text{ GHz}$ @ $\leq 3.0\text{ GHz}$		0.209 0.200 0.197 0.220 0.232 0.348	0.5 0.5 0.4 0.5 0.4 0.6		0.204 0.214 0.213 0.224 0.290 0.545	0.5 0.6 0.5 0.5 0.5 0.8		0.221 0.229 0.243 0.292 0.522 0.911	0.5 0.5 0.4 0.6 0.8 1.3	ps
$t_{\text{jit}(\phi)}$	Additive RMS Phase Jitter $f_c = 156.25\text{ MHz}$ , Integration Range: 12 kHz to 20 MHz (See Figure 5)					60					fs
$V_{\text{PP}}$	Input Swing (Differential Interconnect Configuration) Measured Single-Ended	150	800	1200	150	800	1200	150	800	1200	mV
$t_r/t_f$	Output Rise/Fall Time (20%–80%)	105	200	255	125	200	275	150	230	320	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

14. Measured with 750 mV source, 50% duty cycle clock source. All loading with  $50\ \Omega$  to  $V_{CC} - 2.0\text{ V}$ .

15. Skew is measured between outputs under identical transitions and conditions on any one device.

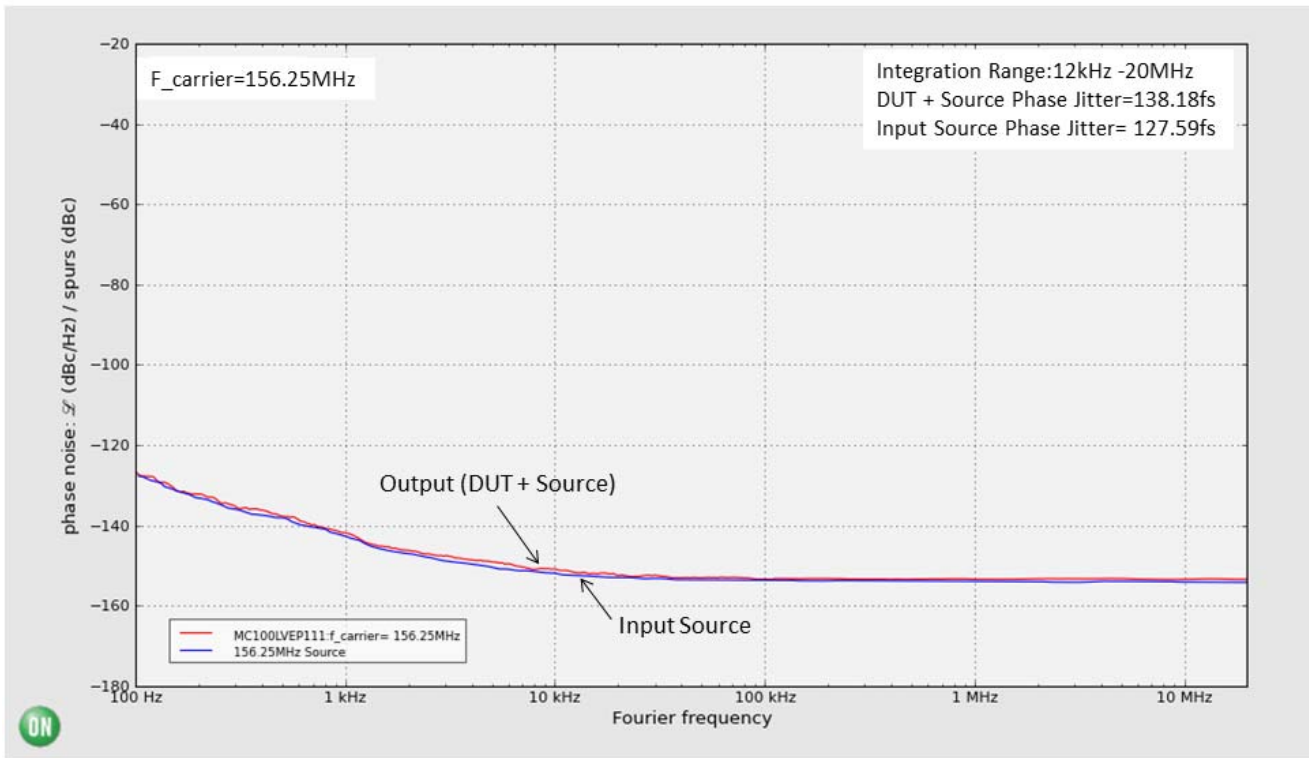
16. Device-to-Device skew for identical transitions at identical  $V_{CC}$  levels.



**Figure 4. F<sub>max</sub> Typical**



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**Figure 5. Typical MC100LVEP111 Phase Noise Plot at  $f_{\text{Carrier}} = 156.25 \text{ MHz}$ ,  $V_{\text{CC}} = 3.3 \text{ V}$ ,  $25^\circ\text{C}$**

The above phase noise data was captured using Agilent E5052A/B. The data displays the input phase noise and output phase noise used to calculate the additive phase jitter at a specified integration range. The additive RMS phase jitter contributed by the device (integrated between 12 kHz and 20 MHz) is 53 fs. The additive RMS phase jitter performance of the fanout buffer is highly dependent on the phase noise of the input source.

To obtain the most precise additive phase noise measurement, it is vital that the source phase noise be

notably lower than that of the DUT. If the phase noise of the source is greater than the noise floor of the device under test, the source noise will dominate the additive phase jitter calculation and lead to an incorrect negative result for the additive phase noise within the integration range. The Figure above is a good example of the MC100LVEP111 source generator phase noise having a significantly lower floor than the DUT and results in an additive phase jitter of 53 fs.

$$\text{Additive RMS phase jitter} = \sqrt{\text{RMS phase jitter of output}^2 - \text{RMS phase jitter of input}^2}$$

$$53 \text{ fs} = \sqrt{138.18 \text{ fs}^2 - 127.59 \text{ fs}^2}$$

Figure 5 was created with measured data from Agilent–E5052B Signal Source Analyzer using ON Semiconductor Phase Noise Explorer web tool. This free application enables an interactive environment for advanced

phase noise and jitter analysis of timing devices and clock tree designs. To see the performance of MC100LVEP111 beyond conditions outlined in this datasheet, please visit the ON Semiconductor [Green Point Design Tools](#) homepage.

# MC100LVEP111

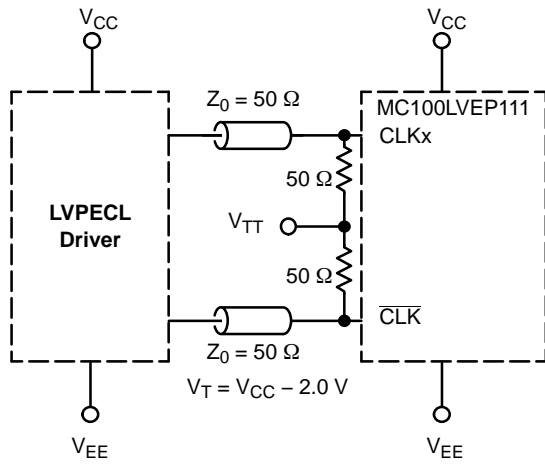


Figure 6. LVPECL in Interface

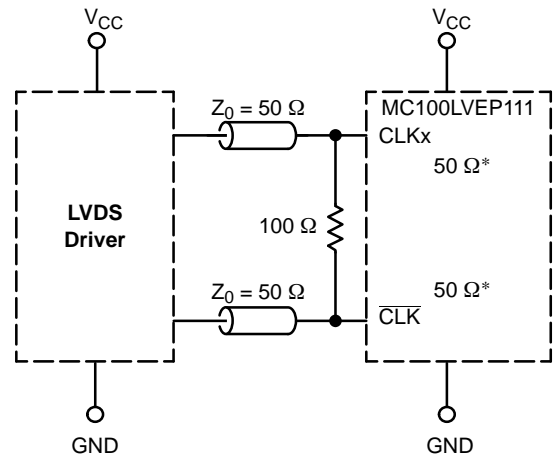


Figure 7. LVDS in Interface

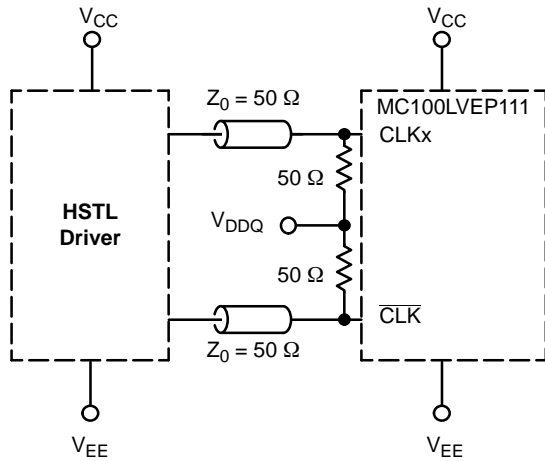


Figure 8. HSTL in Interface

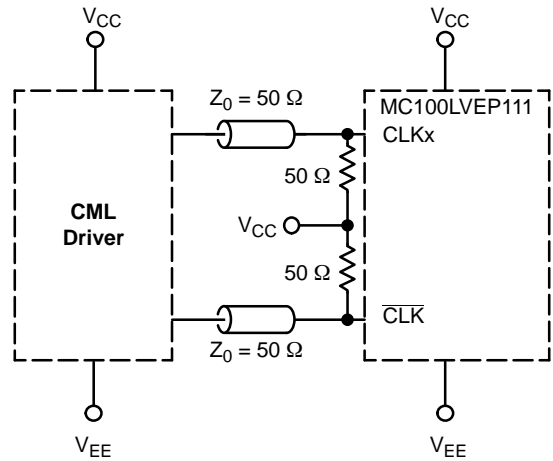


Figure 9. Standard 50 Ω Load CML in Interface

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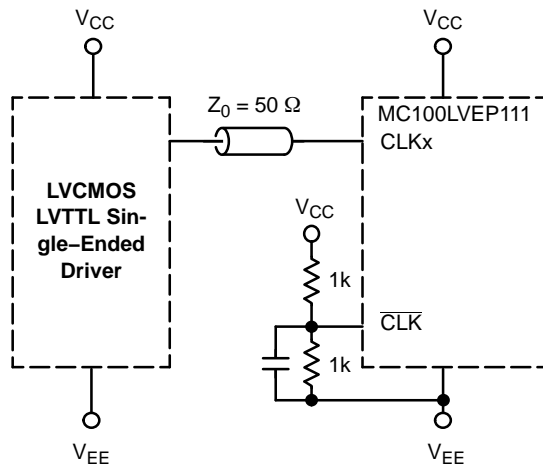


Figure 10. Single-Ended Interface LVC MOS/LVTTL in Interface Using an External Voltage Reference

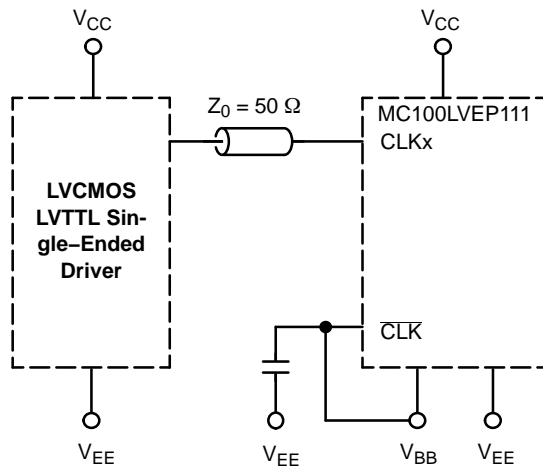
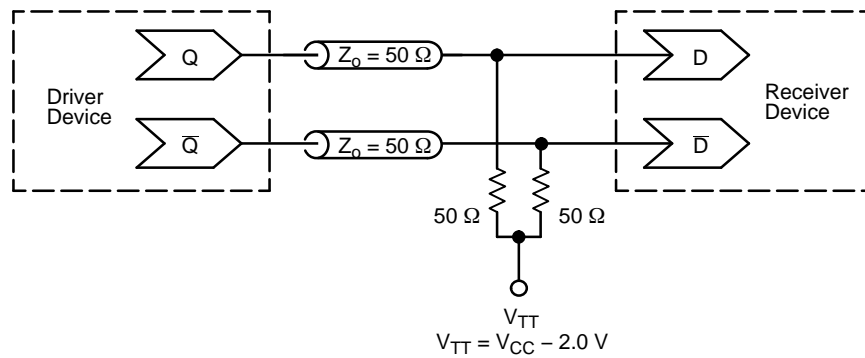
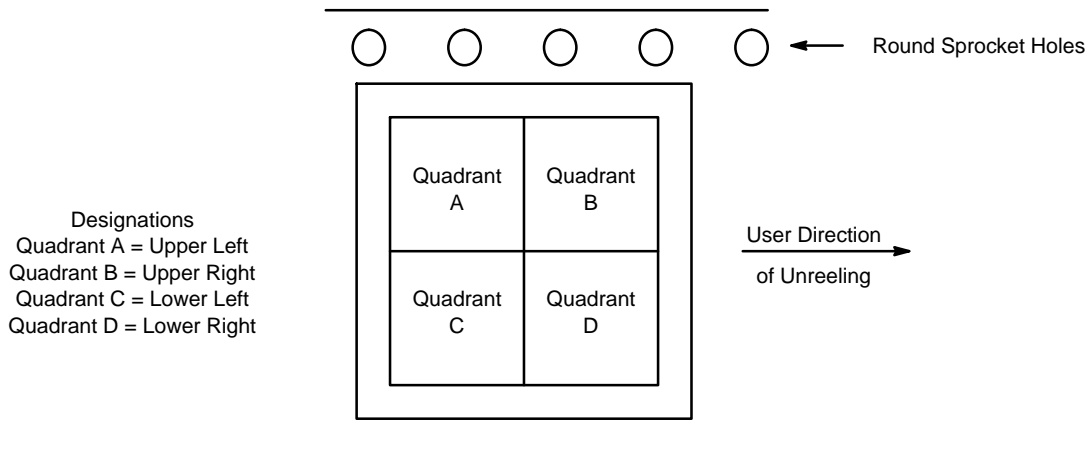


Figure 11. Single-Ended Interface LVC MOS/LVTTL in Interface Using V<sub>BB</sub>

## MC100LVEP111



**Figure 12. Typical Termination for Output Driver and Device Evaluation**  
(See Application Note AND8020/D – Termination of ECL Logic Devices.)



**Figure 13. Tape and Reel Pin 1 Quadrant Orientation**

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC100LVEP111FAG	LQFP-32 (Pb-Free)	250 Units / Tray
MC100LVEP111FARG	LQFP-32 (Pb-Free)	2000 / Tape & Reel (Pin 1 Orientation in Quadrant B, Figure 13)
M100LVEP111FATWG	LQFP-32 (Pb-Free)	2000 / Tape & Reel (Pin 1 Orientation in Quadrant A, Figure 13)
MC100LVEP111MNG	QFN-32 (Pb-Free)	74 Units / Rail
MC100LVEP111MNRG	QFN-32 (Pb-Free)	1000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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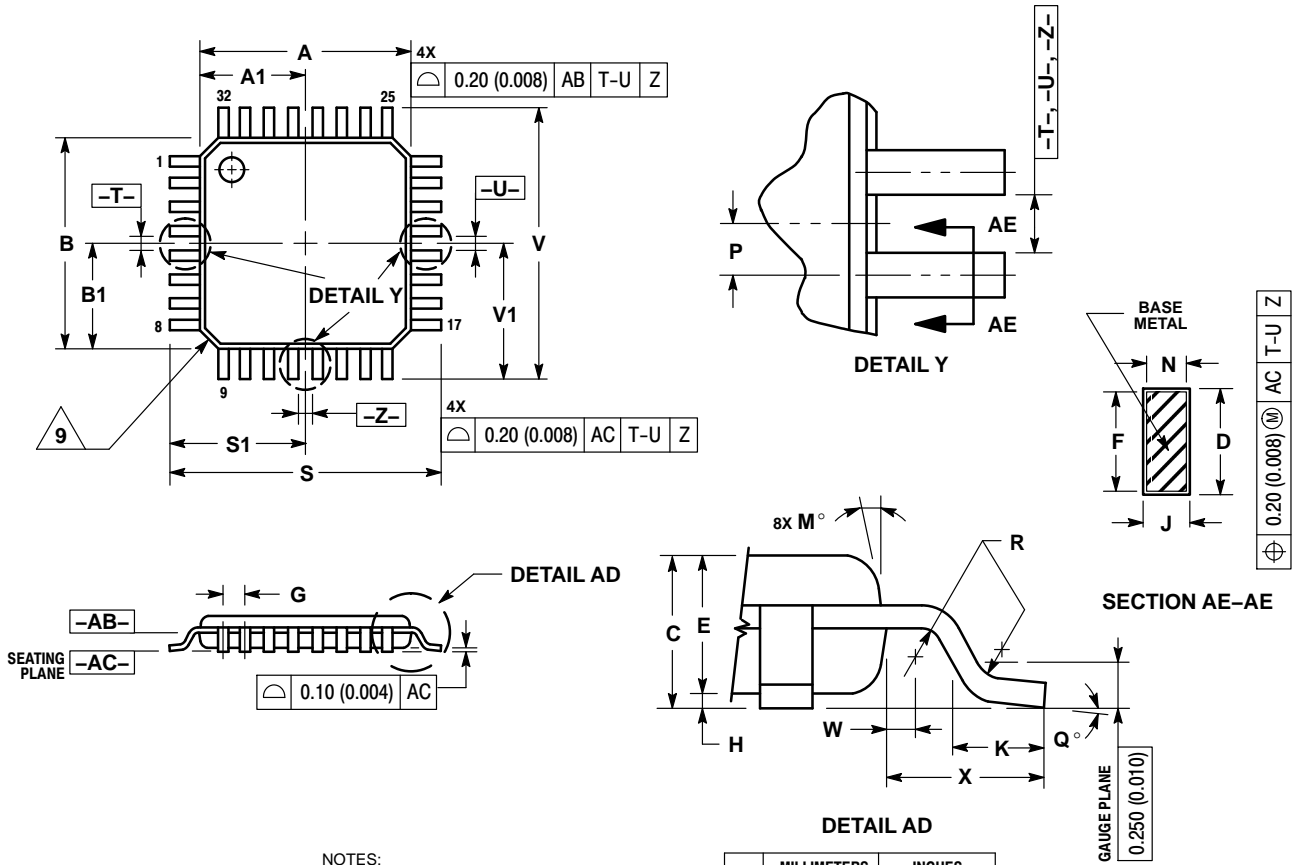
## Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPiCE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

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## PACKAGE DIMENSIONS

32 LEAD LQFP  
CASE 873A-02  
ISSUE C



### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- DATUM PLANE -AB- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
- DATUMS -T-, -U-, AND -Z- TO BE DETERMINED AT DATUM PLANE -AB-.
- DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE -AC-.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -AB-.
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.520 (0.020).
- MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).
- EXACT SHAPE OF EACH CORNER MAY VARY FROM DEPICTION.